

WHAT IS CLAIMED IS:

1. A method for testing semiconductor devices, comprising:
 placing a plurality of semiconductor devices in respective pockets of a tray,
 each of the semiconductor devices having a terminal surface and a plurality of bump terminals
 arranged on the terminal surface, the semiconductor devices being placed in the pockets with
 their respective terminal surfaces facing upward;
 adjusting, relative to the tray, positions of the bump terminals of the
 semiconductor devices;
 successively moving said tray such that the bump terminals of the
 semiconductor devices placed in the pockets of the tray are successively placed at a testing
 position; and
 successively testing the semiconductor devices at the testing position.
2. The method according to claim 1, further comprising, after the adjusting,
 detachably fixing the semiconductor devices to the tray, and then moving the tray.
3. The method according to claim 1, wherein the successively testing comprises
 providing a test head having test electrodes at the testing position, and successively contacting
 the test electrodes to the bump terminals of the semiconductor devices placed at the testing
 position.
4. The method according to claim 1, wherein the successively testing comprises
 successively testing shapes of the bump terminals of the semiconductor devices placed at the
 testing position.
5. The method according to claim 1, wherein the adjusting includes:
 providing a terminal-position adjusting jig having an adjusting surface; and
 pressing the terminal-position adjusting jig against the bump terminals of the
 semiconductor devices placed in the pockets of the tray so that the adjusting surface engages
 with the bump terminals of the semiconductor devices.
6. The method according to claim 5, wherein the adjusting further includes
 vibrating at least one of the terminal-position adjusting jig and the tray while pressing the
 terminal-position adjusting jig against the bump terminals.
7. An apparatus for testing semiconductor devices, comprising:
 a terminal-position adjusting unit for adjusting positions of bump terminals
 arranged on terminal surfaces of semiconductor devices, the semiconductor devices being
 placed in pockets of a tray with their respective terminal surfaces facing upward; and

a moving unit for successively moving the tray such that the bump terminals of the semiconductor devices placed in the pockets of the tray are successively placed in a testing position.

8. The apparatus according to claim 7, further comprising a fixing unit for detachably fixing the semiconductor devices to the tray.

9. The apparatus according to claim 7, wherein the terminal-position adjusting unit comprises a driving unit for pressing a terminal-position adjusting jig, having an adjusting surface, against the bump terminals of the semiconductor devices placed in the pockets of the tray so that the adjusting surface engages with the bump terminals.

10. The apparatus according to claim 8, wherein:
the tray has openings at bottoms of the pockets, and
the fixing unit fixes the semiconductor devices by attaching an adhesive tape to the semiconductor devices through the openings.